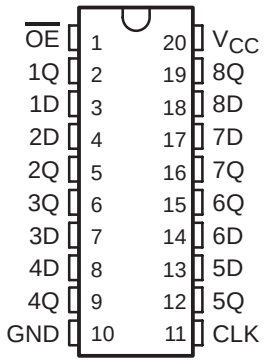
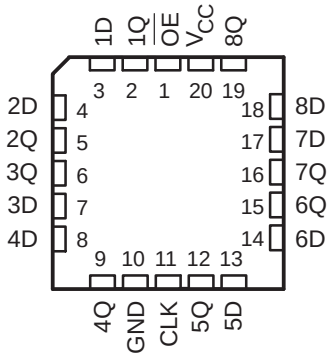
- **Eight D-Type Flip-Flops in a Single Package**
- **3-State Bus-Driving True Outputs**
- **Full Parallel Access for Loading**
- **Buffered Control Inputs**
- **Package Options Include Plastic Small-Outline (SOIC) and Shrink Small-Outline (SSOP) Packages, Ceramic Chip Carriers, and Plastic and Ceramic DIPs**

SN54F374 . . . J PACKAGE
SN74F374 . . . DB, DW, OR N PACKAGE
(TOP VIEW)



SN54F374 . . . FK PACKAGE
(TOP VIEW)



description

These 8-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight flip-flops of the ′F374 are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels that were set up at the data (D) inputs.

A buffered output enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

The output enable ($\overline{OE}$) input does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN74F374 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54F374 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74F374 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE
(each flip-flop)

INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q_0
H	X	X	Z

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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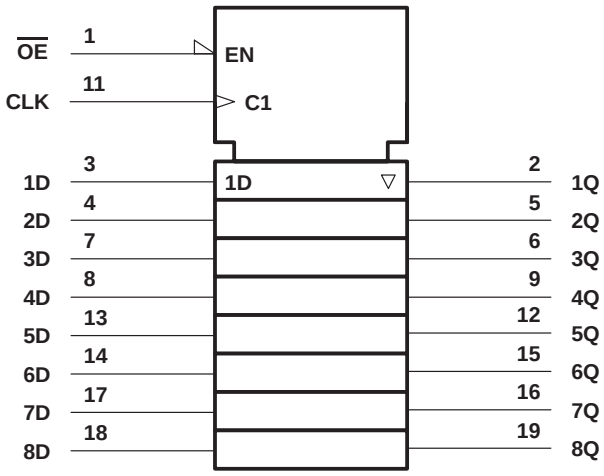
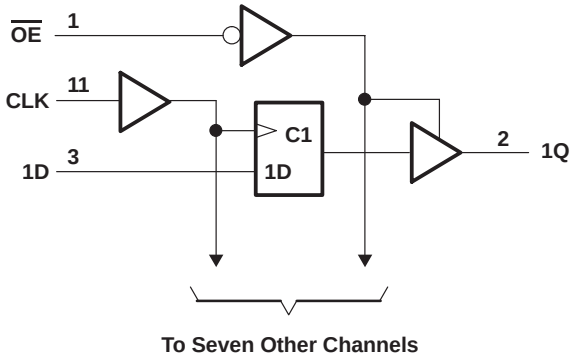
logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} . . . . . −0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . −1.2 V to 7 V
Input current range . . . . . −30 mA to 5 mA
Voltage range applied to any output in the disabled or power-off state . . . . . −0.5 V to 5.5 V
Voltage range applied to any output in the high state . . . . . −0.5 V to V_{CC}
Current into any output in the low state: SN54F374 . . . . . 40 mA
SN74F374 . . . . . 48 mA
Operating free-air temperature range: SN54F374 . . . . . −55°C to 125°C
SN74F374 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions

		SN54F374			SN74F374			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{IK}	Input clamp current			−18			−18	mA
I_{OH}	High-level output current			−3			−3	mA
I_{OL}	Low-level output current			20			24	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54F374			SN74F374			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = −18 mA			−1.2			−1.2	V
V_{OH}	V_{CC} = 4.5 V	I_{OH} = − 1 mA	2.5	3.4		2.5	3.4		V
		I_{OH} = − 3 mA	2.4	3.3		2.4	3.3		
	V_{CC} = 4.75 V,	I_{OH} = − 1 mA to −3 mA				2.7			
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 20 mA		0.3	0.5				V
		I_{OL} = 24 mA					0.35	0.5	
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V			50			50	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V			−50			−50	µA
I_I	V_{CC} = 5.5 V,	V_I = 7 V			0.1			0.1	mA
I_{IH}	V_{CC} = 5.5 V,	V_I = 2.7 V			20			20	µA
I_{IL}	V_{CC} = 5.5 V,	V_I = 0.5 V			− 0.6			− 0.6	mA
I_{OS}‡	V_{CC} = 5.5 V,	V_O = 0	−60		−150	−60		−150	mA
I_{CCZ}	V_{CC} = 5.5 V,	See Note 2		55	86		55	86	mA

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.
NOTE 2: I_{CCZ} is measured with $\overline{OE}$ at 4.5 V and all other inputs grounded.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			V_{CC} = 5 V, T_A = 25°C		SN54F374		SN74F374		UNIT
			′F374						
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	100	0	60	0	70	MHz
t_w	Pulse duration	CLK high	7		7		7		ns
		CLK low	6		6		6		
t_{su}	Setup time, data before CLK↑	High	2		2.5		2		ns
		Low	2		2		2		
t_h	Hold time, data after CLK↑	High	2		2		2		ns
		Low	2		2.5		2		

switching characteristics (see Note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, C_L = 50 pF, R_L = 500 Ω, T_A = 25°C			V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R_L = 500 Ω, T_A = MIN to MAX†				UNIT
			′F374			SN54F374		SN74F374		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			100			60		70		MHz
t_{PLH}	CLK	Q	3.2	6.1	8.5	3.2	10.5	3.2	10	ns
t_{PHL}			3.2	6.1	8.5	3.2	11	3.2	10	
t_{PZH}	$\overline{OE}$	Q	1.2	8.6	11.5	1.2	14	1.2	12.5	ns
t_{PZL}			1.2	5.4	7.5	1.2	10	1.2	8.5	
t_{PHZ}	$\overline{OE}$	Q	1.2	4.9	7	1.2	8	1.2	8	ns
t_{PLZ}			1.2	3.9	5.5	1.2	7.5	1.2	6.5	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
NOTE 3: Load circuits and waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-9759001Q2A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9759001Q2A SNJ54F374FK
5962-9759001QRA	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9759001QRA SNJ54F374J
5962-9759001QSA	Active	Production	CFP (W) | 20	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9759001QSA SNJ54F374W
JM38510/34105B2A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/34105B2A
JM38510/34105B2A.A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/34105B2A
JM38510/34105BRA	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/34105BRA
JM38510/34105BRA.A	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/34105BRA
JM38510/34105BSA	Active	Production	CFP (W) | 20	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/34105BSA
JM38510/34105BSA.A	Active	Production	CFP (W) | 20	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/34105BSA
M38510/34105B2A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/34105B2A
M38510/34105BRA	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/34105BRA
M38510/34105BSA	Active	Production	CFP (W) | 20	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/34105BSA
SN54F374J	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54F374J
SN54F374J.A	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54F374J
SN74F374DBR	Active	Production	SSOP (DB) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F374
SN74F374DBR.A	Active	Production	SSOP (DB) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F374
SN74F374DW	Obsolete	Production	SOIC (DW) | 20	-	-	Call TI	Call TI	0 to 70	F374

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74F374DWR	Active	Production	SOIC (DW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F374
SN74F374DWR.A	Active	Production	SOIC (DW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F374
SN74F374N	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F374N
SN74F374N.A	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F374N
SN74F374NSR	Active	Production	SOP (NS) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F374
SN74F374NSR.A	Active	Production	SOP (NS) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F374
SNJ54F374FK	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9759001Q2A SNJ54F 374FK
SNJ54F374FK.A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9759001Q2A SNJ54F 374FK
SNJ54F374J	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9759001QRA SNJ54F374J
SNJ54F374J.A	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9759001QRA SNJ54F374J
SNJ54F374W	Active	Production	CFP (W) | 20	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9759001QSA SNJ54F374W
SNJ54F374W.A	Active	Production	CFP (W) | 20	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9759001QSA SNJ54F374W

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54F374, SN74F374 :

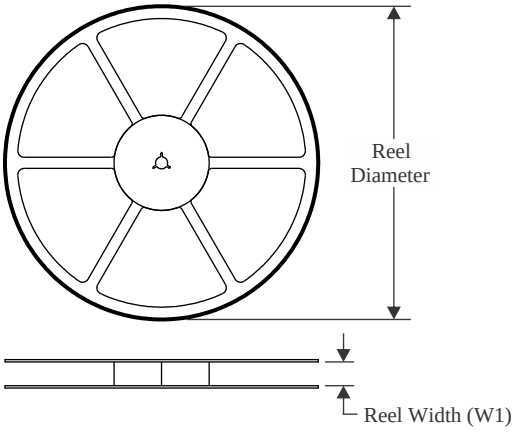
- Catalog : SN74F374
- Military : SN54F374

NOTE: Qualified Version Definitions:

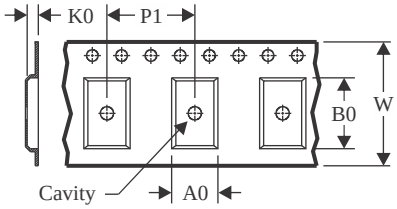
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

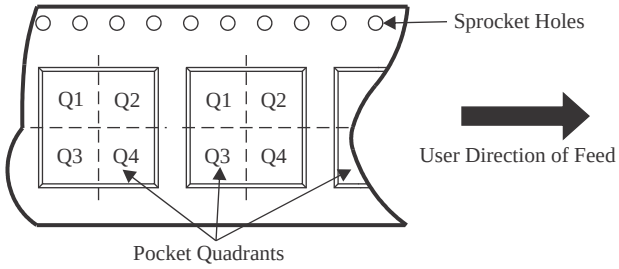


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

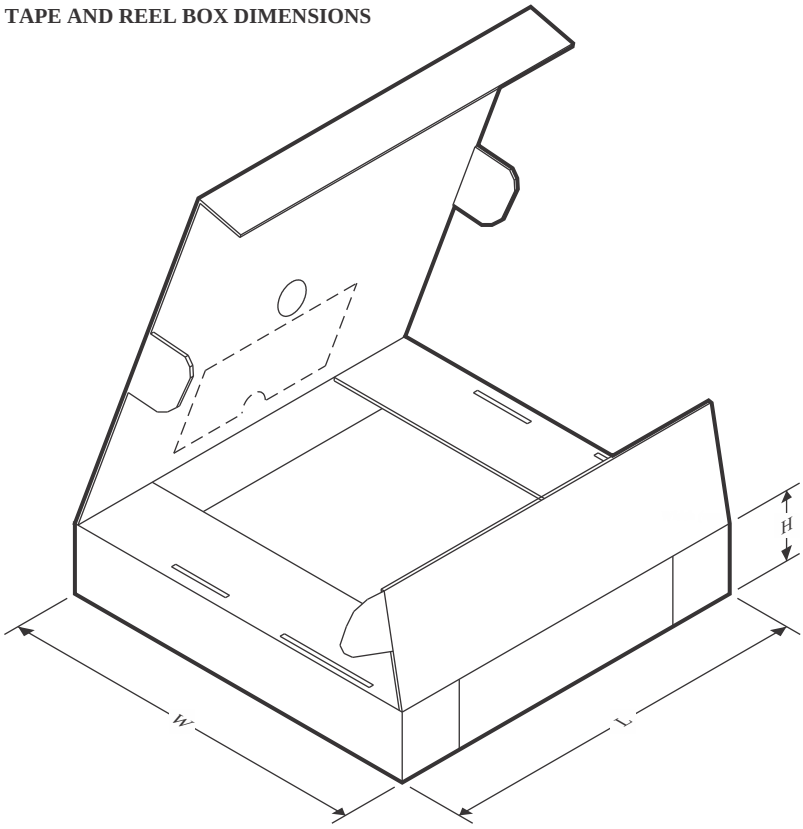
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F374DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74F374DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74F374NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

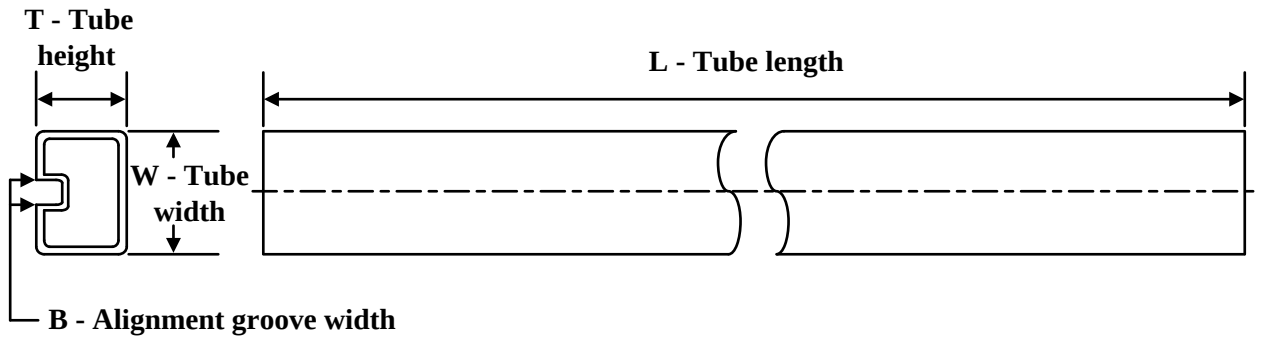
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F374DBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN74F374DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74F374NSR	SOP	NS	20	2000	356.0	356.0	45.0

TUBE



*All dimensions are nominal

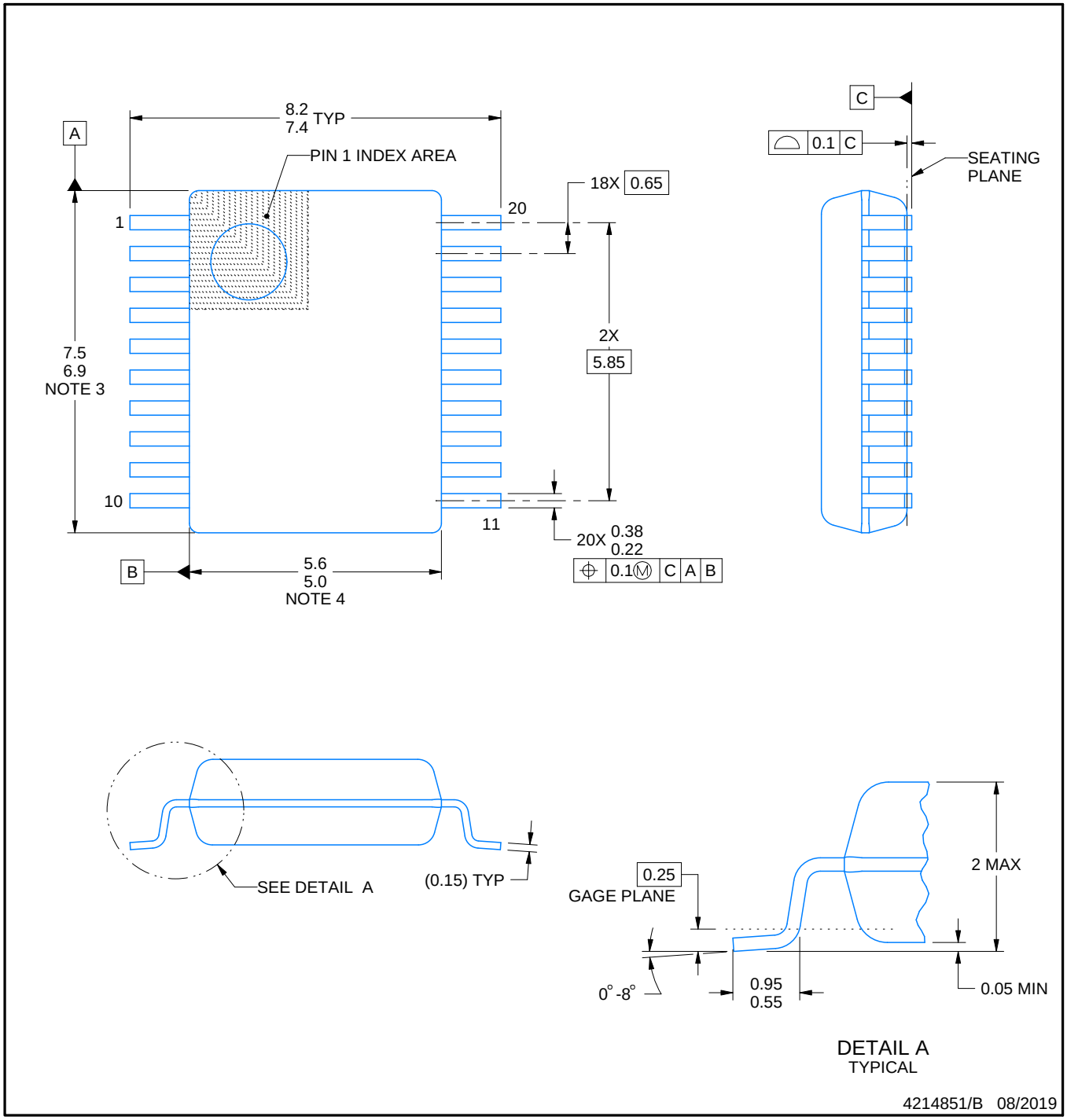
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9759001Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9759001QSA	W	CFP	20	25	506.98	26.16	6220	NA
JM38510/34105B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/34105B2A.A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/34105BSA	W	CFP	20	25	506.98	26.16	6220	NA
JM38510/34105BSA.A	W	CFP	20	25	506.98	26.16	6220	NA
M38510/34105B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
M38510/34105BSA	W	CFP	20	25	506.98	26.16	6220	NA
SN74F374N	N	PDIP	20	20	506	13.97	11230	4.32
SN74F374N.A	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54F374FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54F374FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54F374W	W	CFP	20	25	506.98	26.16	6220	NA
SNJ54F374W.A	W	CFP	20	25	506.98	26.16	6220	NA

PACKAGE OUTLINE

DB0020A

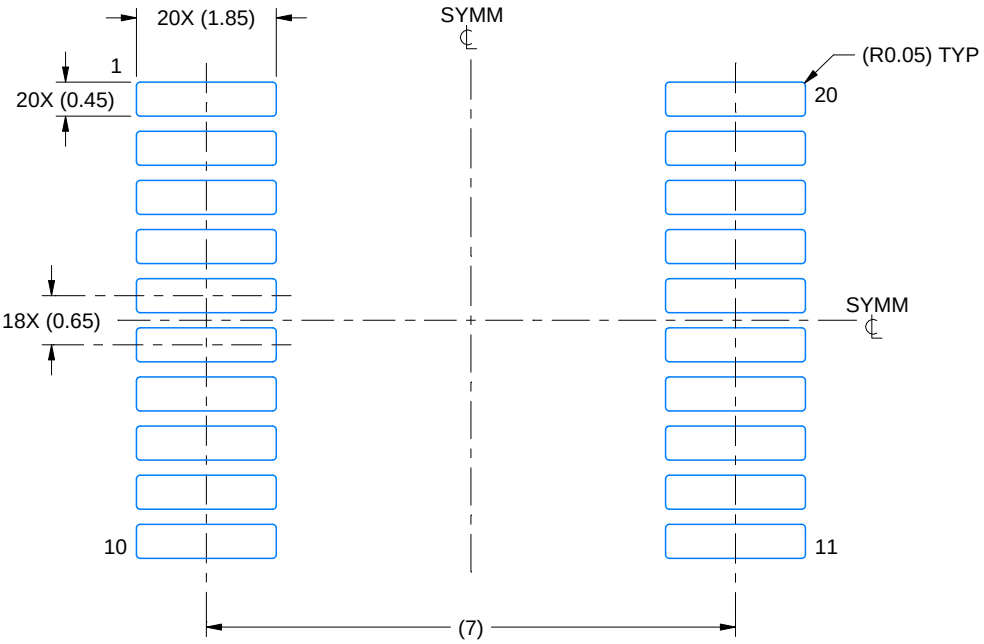
SSOP - 2 mm max height

SMALL OUTLINE PACKAGE

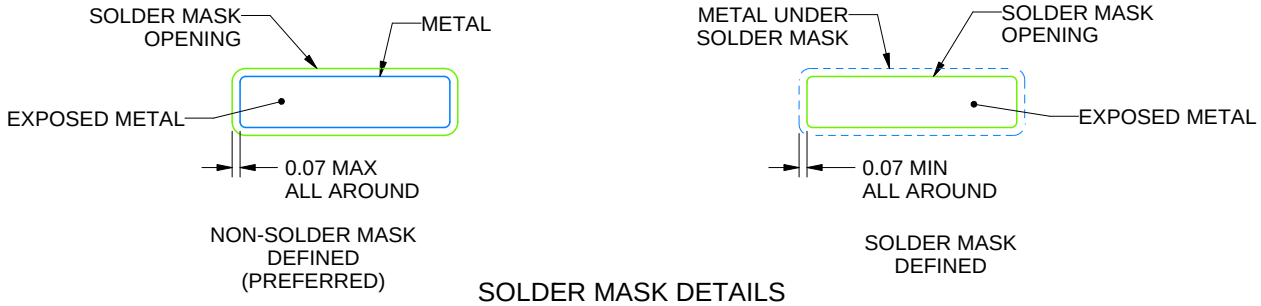


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

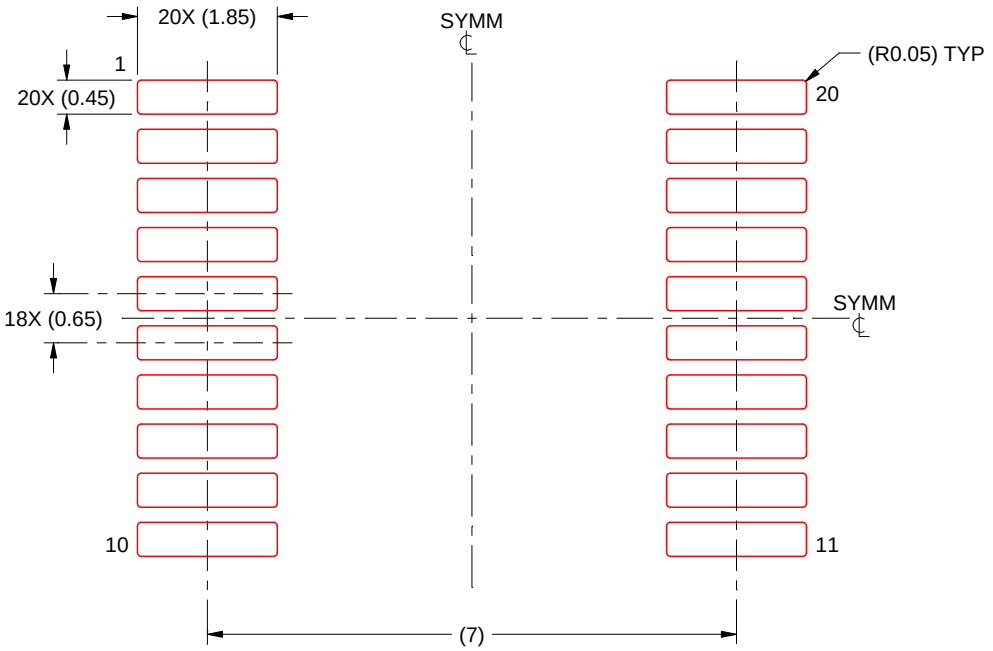
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

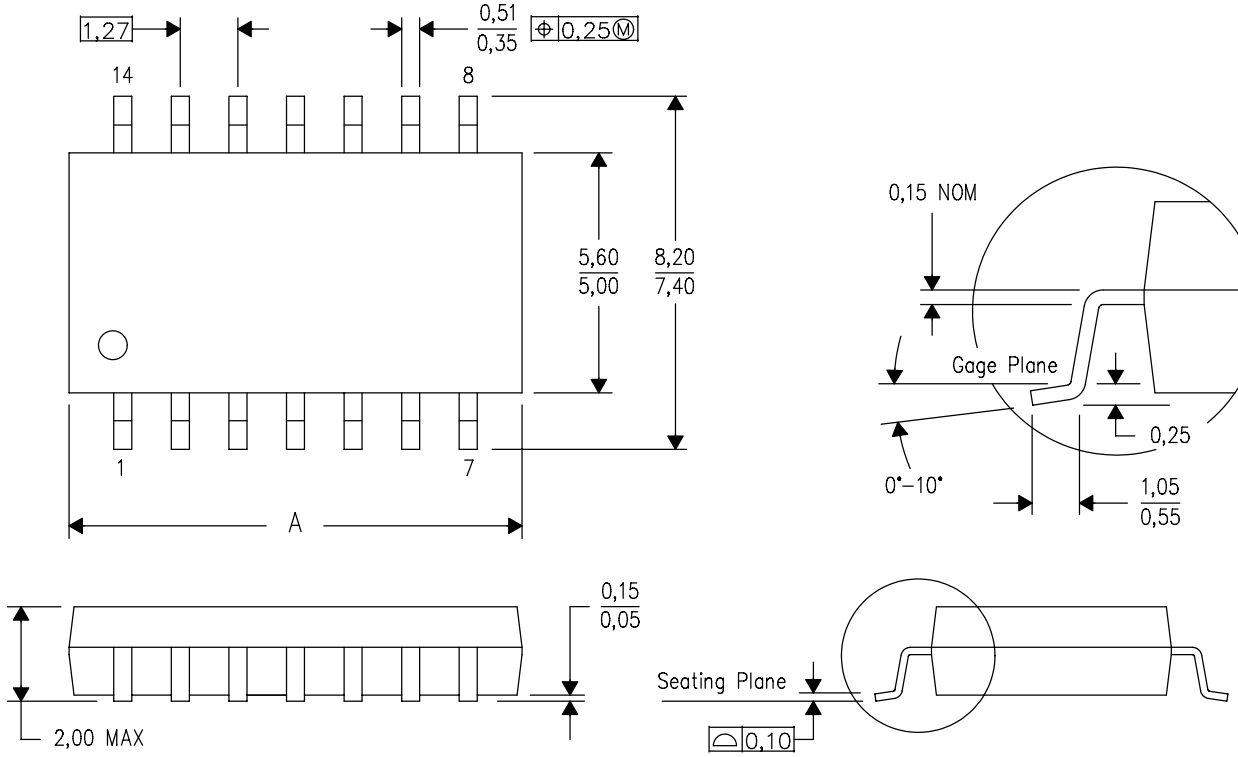
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

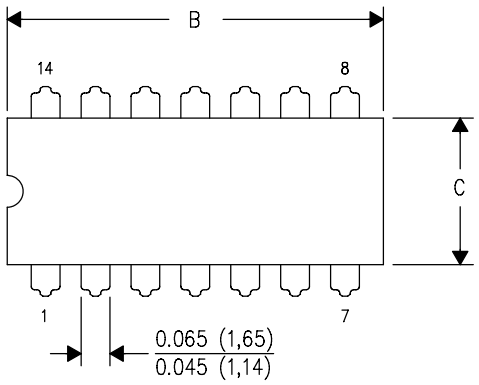
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

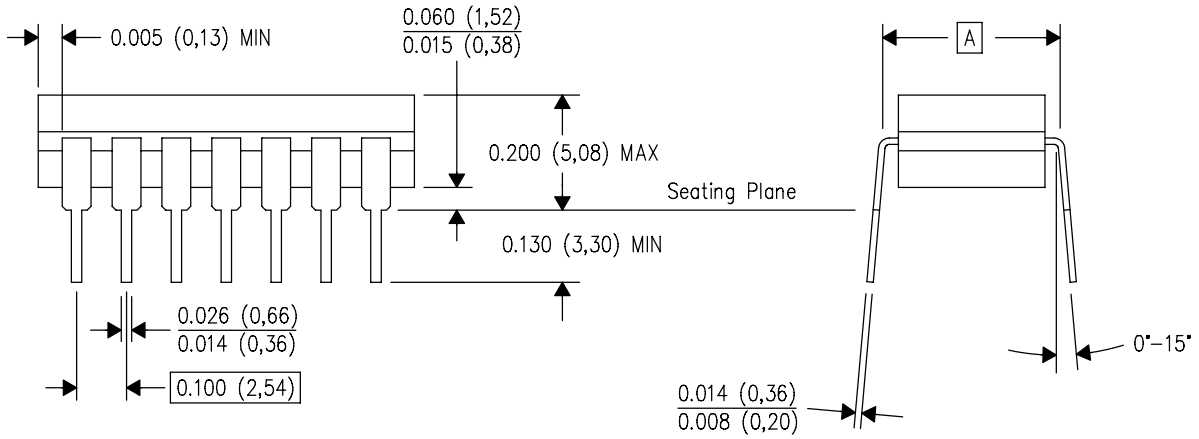
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

GENERIC PACKAGE VIEW

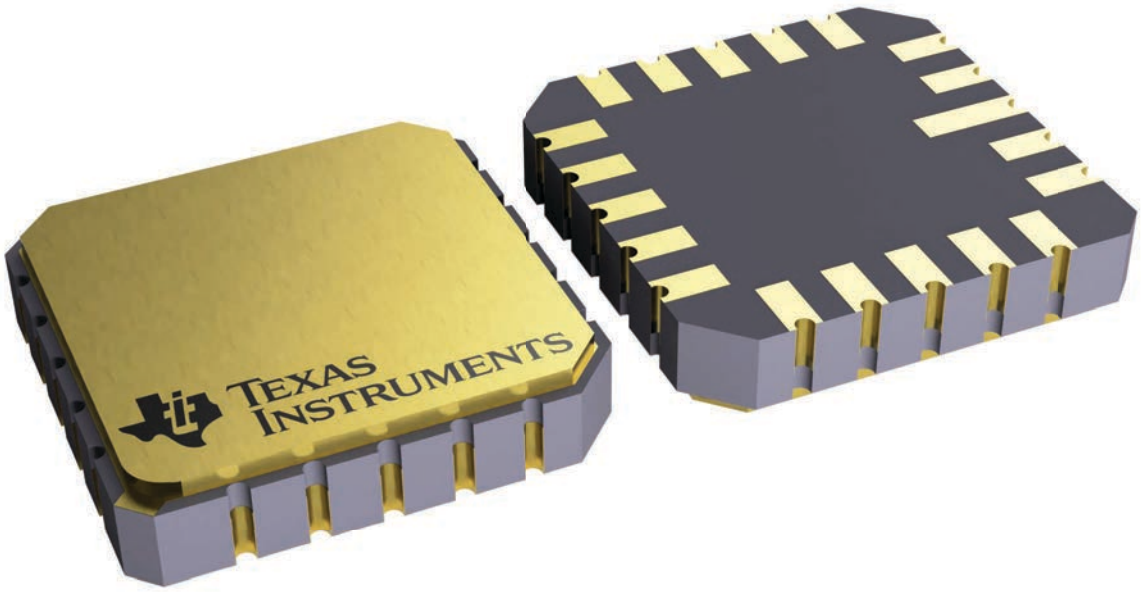
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

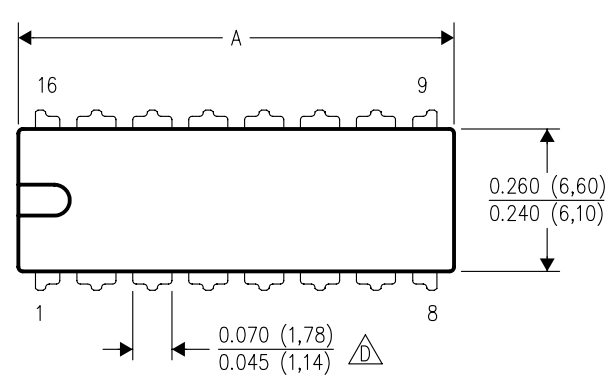


4229370VA\

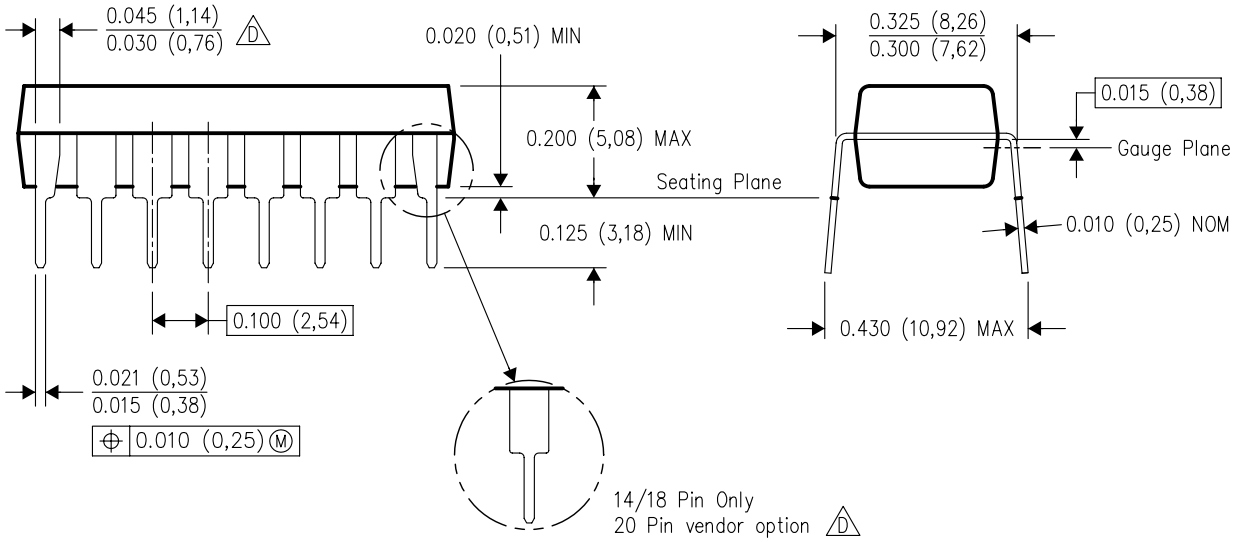
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

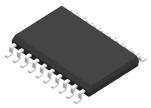


DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

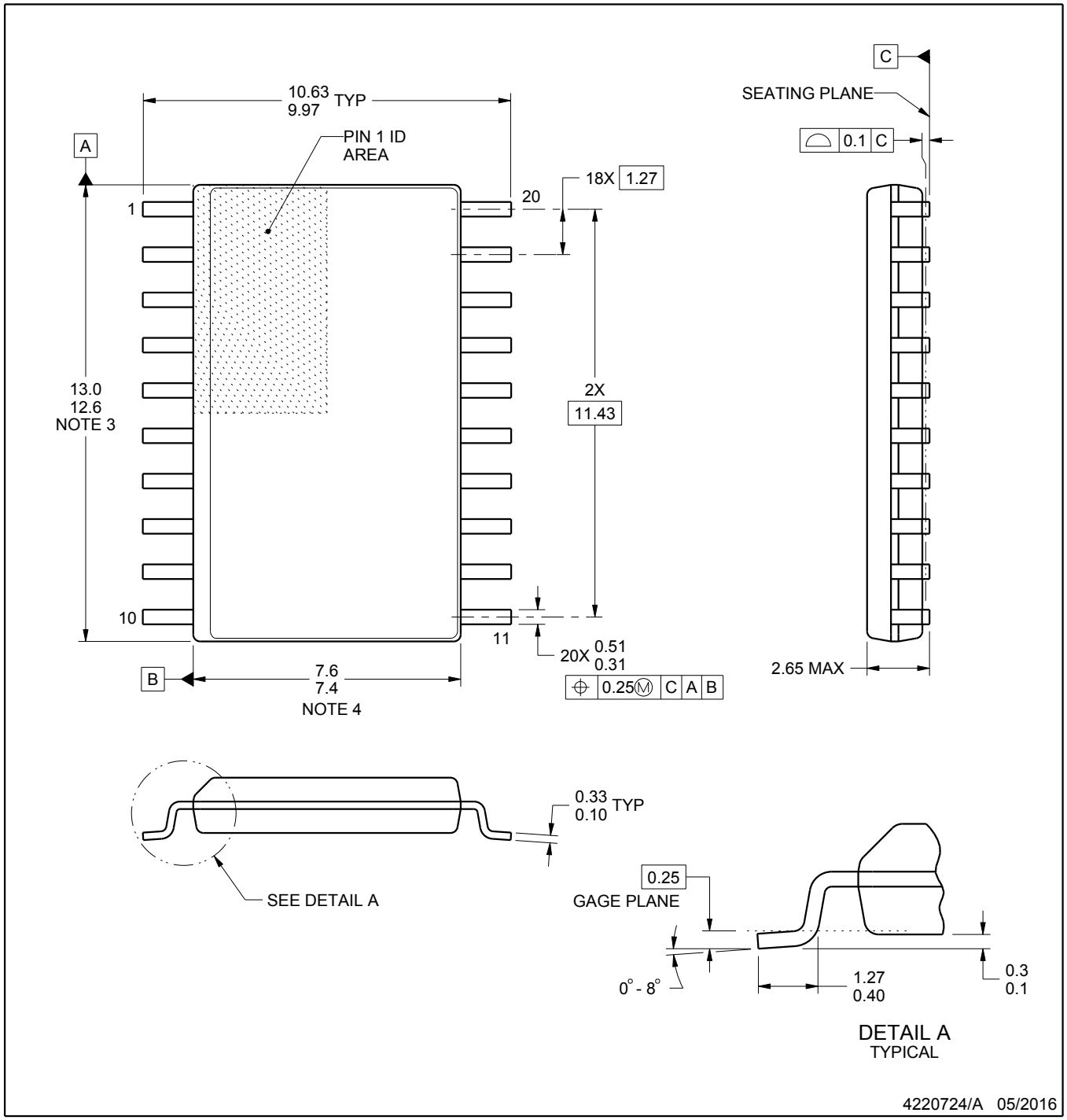


PACKAGE OUTLINE

DW0020A

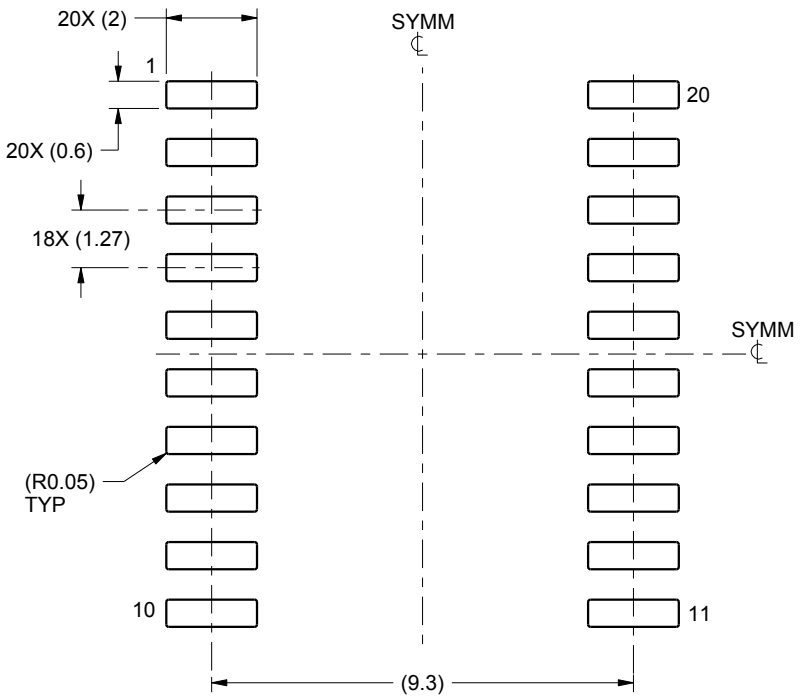
SOIC - 2.65 mm max height

SOIC

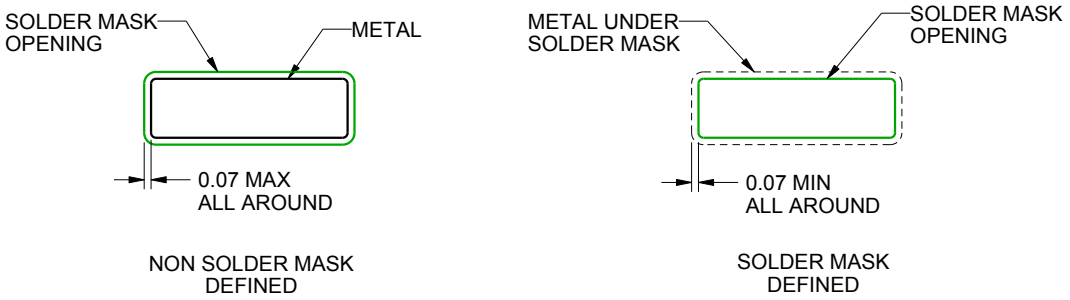


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:6X

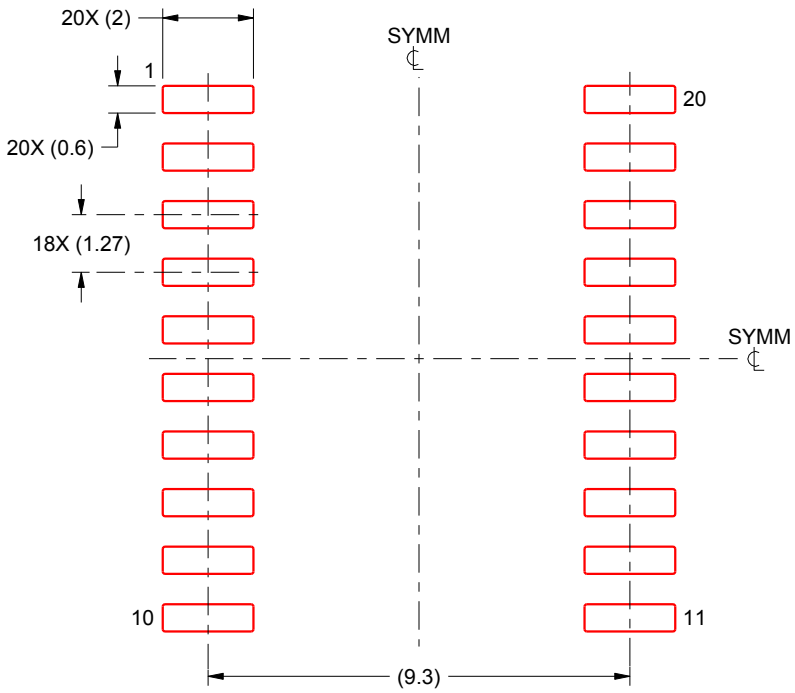


SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



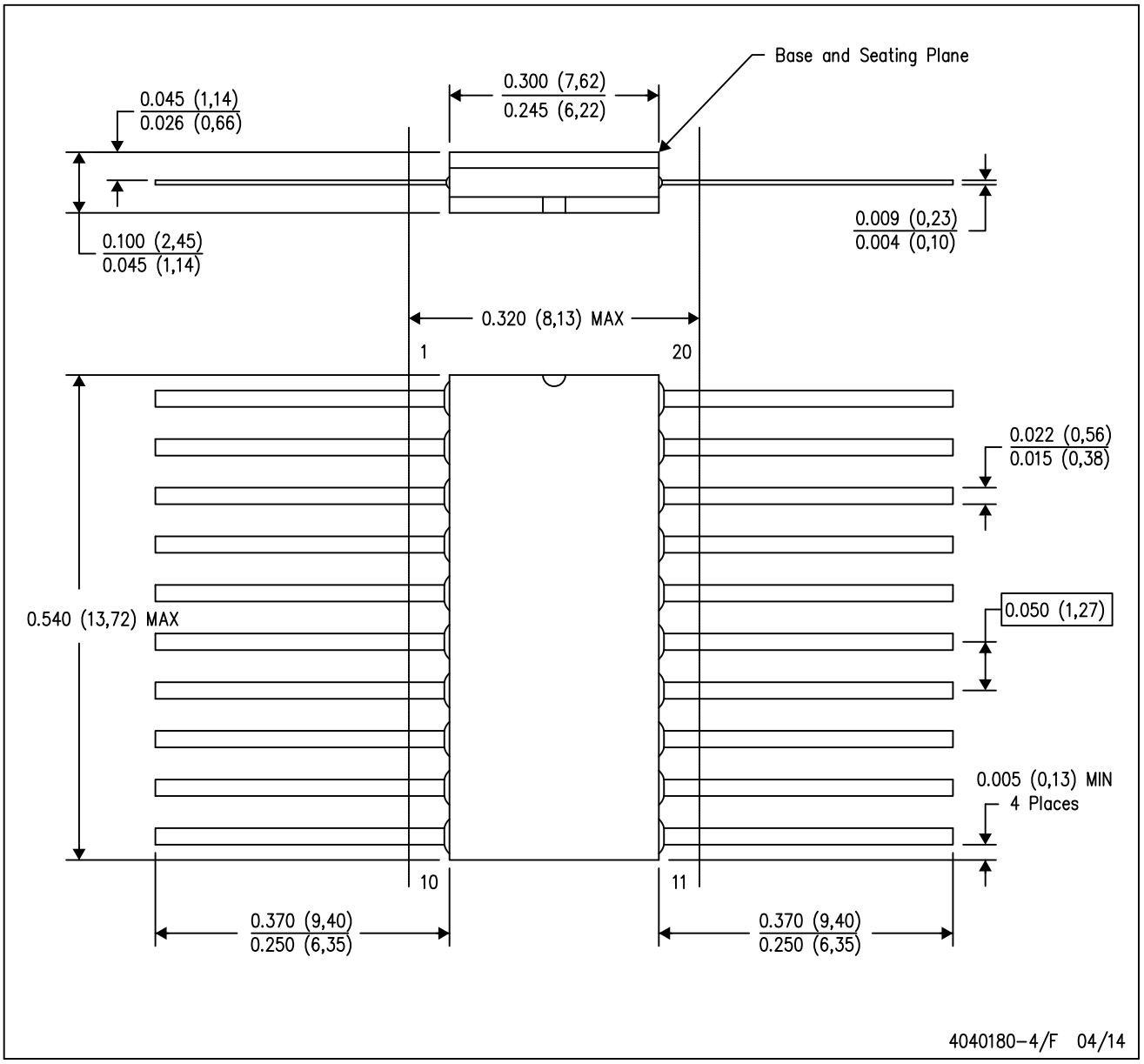
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

W (R–GDFP–F20) CERAMIC DUAL FLATPACK



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within Mil–Std 1835 GDFP2–F20

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